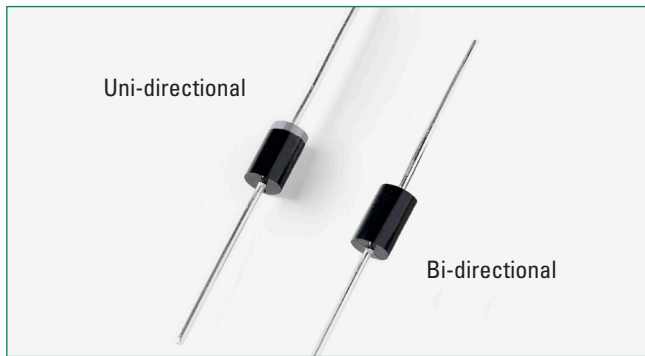


**TP1.5KE Series**



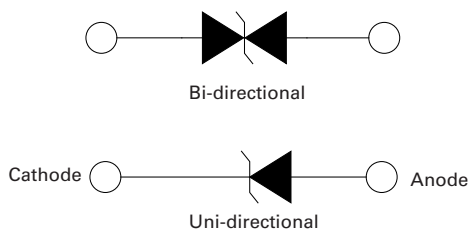
Agency Approvals	
Agency	Agency File Number
	E230531

**Maximum Ratings and Thermal Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation by 10/1000µs Test Waveform (Fig.2)(Note 1)	P <sub>PPM</sub>	1500	W
Steady State Power Dissipation on Infinite Heat Sink at T <sub>L</sub> =75°C	P <sub>D</sub>	6.5	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave Unidirectional Only (Note 2)	I <sub>FSM</sub>	200	A
Maximum Instantaneous Forward Voltage at 100A for Unidirectional Only (Note 3)	V <sub>F</sub>	3.5	V
Operating Junction Temperature Range	T <sub>J</sub>	-55 to 150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to 175	°C
Typical Thermal Resistance Junction to Lead	R <sub>JL</sub>	15	°C/W
Typical Thermal Resistance Junction to Ambient	R <sub>JA</sub>	75	°C/W

- Notes:**  
 1. Non-repetitive current pulse, per Fig. 4 and derated above T<sub>J</sub> (initial) = 25°C per Fig. 3.  
 2. Measured on 8.3ms single half sine wave or equivalent square wave, duty cycle=4 per minute maximum.

**Functional Diagram**



**Description**

The TP1.5KE Series is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.


**Features**

- High reliability application and automotive grade AEC-Q101 rev D qualified
- Glass passivated chip junction in DO-201 Package
- 1500W peak pulse capability at 10/1000µs waveform, repetition rate (duty cycles):0.01%
- Fast response time: typically less than 1.0ps from 0 Volts to BV min
- Excellent clamping capability
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC 61000-4-2 ESD 30kV(Air), 30kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2
- EFT protection of data lines in accordance with IEC 61000-4-4
- Low incremental surge resistance
- High temperature to reflow soldering guaranteed: 260°C/10sec / 0.375";(9.5mm) lead length, 5 lbs., (2.3kg) tension
- V<sub>BR</sub> @ T<sub>J</sub> = V<sub>BR</sub> @ 25°C x (1 + αT x (T<sub>J</sub> - 25)) (αT: Temperature Coefficient, typical value is 0.1%)
- Plastic package is flammability rated V-0 per Underwriters Laboratories
- Matte tin lead-free plated
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

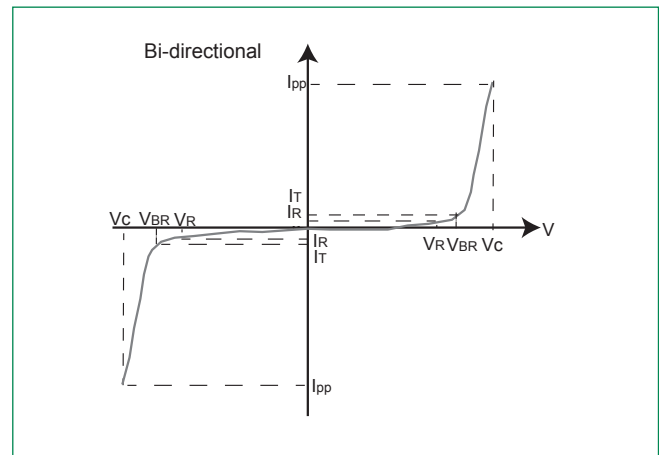
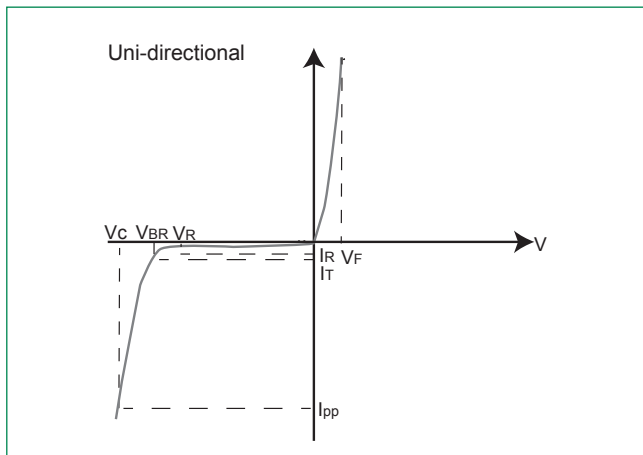
**Applications**

TVS devices are ideal for the protection of I/O interfaces, V<sub>CC</sub> bus and other vulnerable circuits used in telecom, computer, industrial and consumer electronic applications.

### Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Part Number (Uni)	Part Number (Bi)	Reverse Stand off Voltage V <sub>R</sub> (Volts)	Breakdown Voltage V <sub>BR</sub> (Volts) @ I <sub>T</sub>		Test Current I <sub>T</sub> (mA)	Maximum Clamping Voltage V <sub>C</sub> @ I <sub>pp</sub> (Volts)	Maximum Peak Pulse Current I <sub>pp</sub> (A)	Maximum Reverse Leakage I <sub>R</sub> @ V <sub>R</sub> (μA)	Agency Approval 
			MIN	MAX					
TP1.5KE12A	TP1.5KE12CA	10.20	11.40	12.60	1	16.7	91.0	5	X
TP1.5KE13A	TP1.5KE13CA	11.10	12.40	13.70	1	18.2	83.5	1	X
TP1.5KE15A	TP1.5KE15CA	12.80	14.30	15.80	1	21.2	71.7	1	X
TP1.5KE16A	TP1.5KE16CA	13.60	15.20	16.80	1	22.5	67.6	1	X
TP1.5KE18A	TP1.5KE18CA	15.30	17.10	18.90	1	25.2	60.3	1	X
TP1.5KE20A	TP1.5KE20CA	17.10	19.00	21.00	1	27.7	54.9	1	X
TP1.5KE22A	TP1.5KE22CA	18.80	20.90	23.10	1	30.6	49.7	1	X
TP1.5KE24A	TP1.5KE24CA	20.50	22.80	25.20	1	33.2	45.8	1	X
TP1.5KE27A	TP1.5KE27CA	23.10	25.70	28.40	1	37.5	40.5	1	X
TP1.5KE30A	TP1.5KE30CA	25.60	28.50	31.50	1	41.4	36.7	1	X
TP1.5KE33A	TP1.5KE33CA	28.20	31.40	34.70	1	45.7	33.3	1	X
TP1.5KE36A	TP1.5KE36CA	30.80	34.20	37.80	1	49.9	30.5	1	X
TP1.5KE39A	TP1.5KE39CA	33.30	37.10	41.00	1	53.9	28.2	1	X
TP1.5KE43A	TP1.5KE43CA	36.80	40.90	45.20	1	59.3	25.6	1	X
TP1.5KE47A	TP1.5KE47CA	40.20	44.70	49.40	1	64.8	23.5	1	X

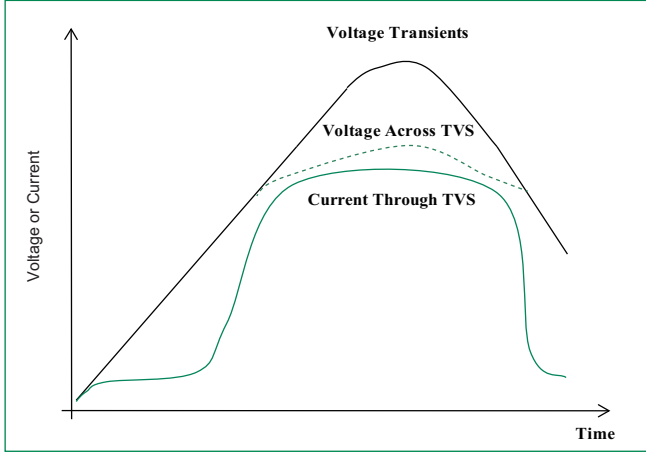
### I-V Curve Characteristics



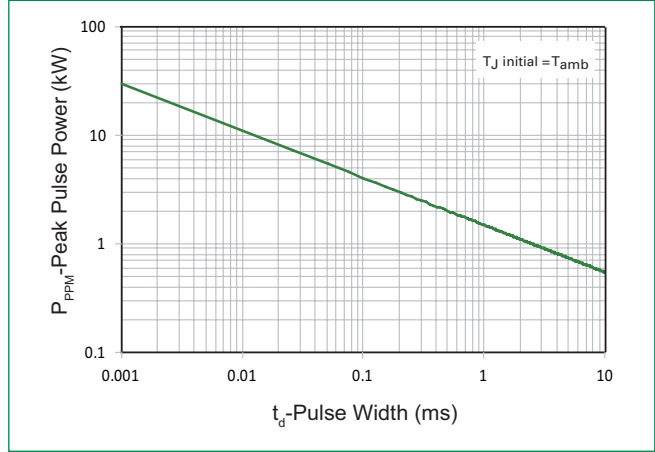
- P<sub>PPM</sub>** Peak Pulse Power Dissipation -- Max power dissipation
- V<sub>R</sub>** Stand-off Voltage -- Maximum voltage that can be applied to the TVS without operation
- V<sub>BR</sub>** Breakdown Voltage -- Maximum voltage that flows through the TVS at a specified test current (I<sub>T</sub>)
- V<sub>C</sub>** Clamping Voltage -- Peak voltage measured across the TVS at a specified I<sub>ppm</sub> (peak impulse current)
- I<sub>R</sub>** Reverse Leakage Current -- Current measured at V<sub>R</sub>
- V<sub>F</sub>** Forward Voltage Drop for Uni-directional

**Ratings and Characteristic Curves** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

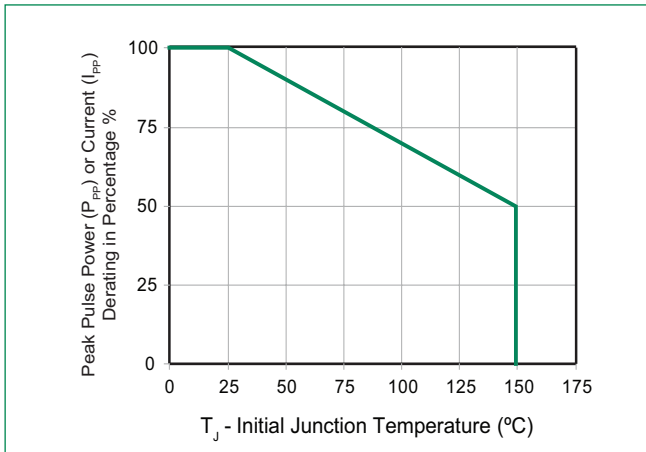
**Figure 1 - TVS Transients Clamping Waveform**



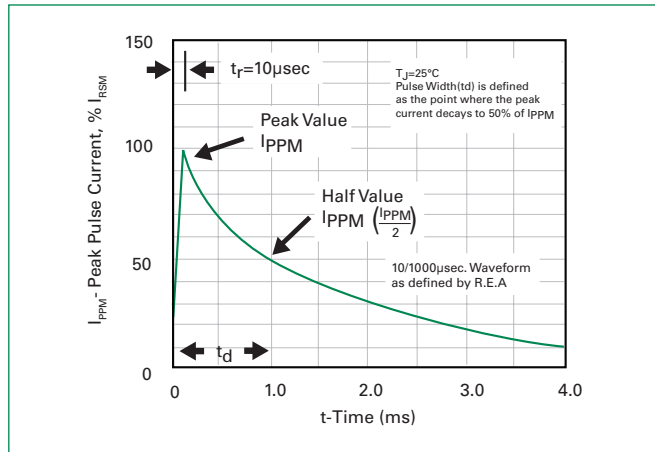
**Figure 2 - Peak Pulse Power Rating**



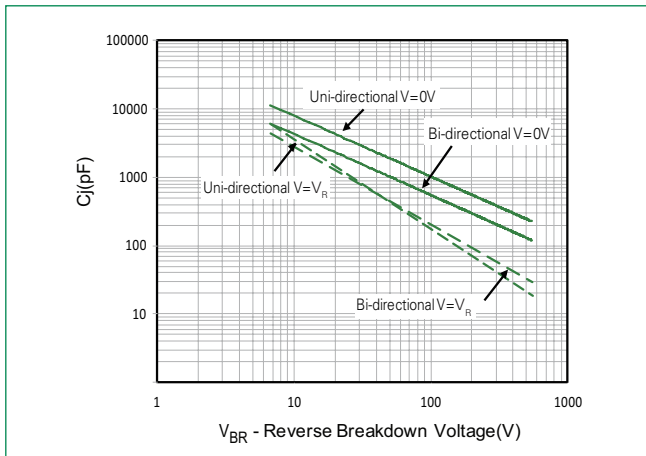
**Figure 3 - Peak Pulse Power Derating Curve**



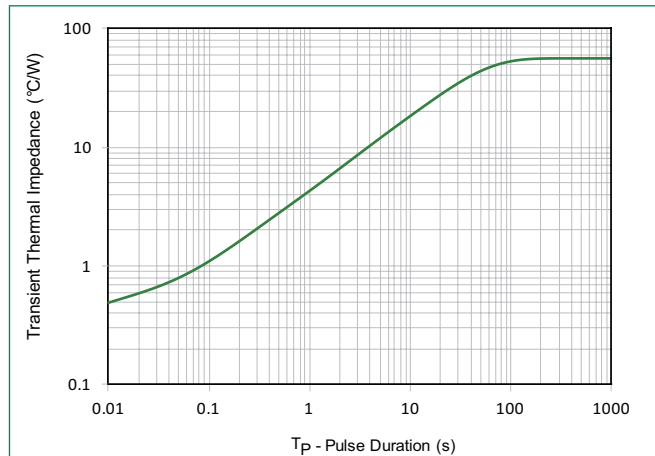
**Figure 4 - Pulse Waveform**



**Figure 5 - Typical Junction Capacitance**

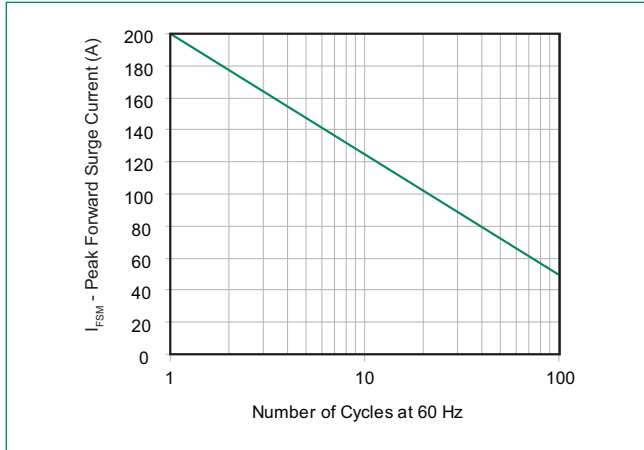


**Figure 6 - Typical Transient Thermal Impedance**

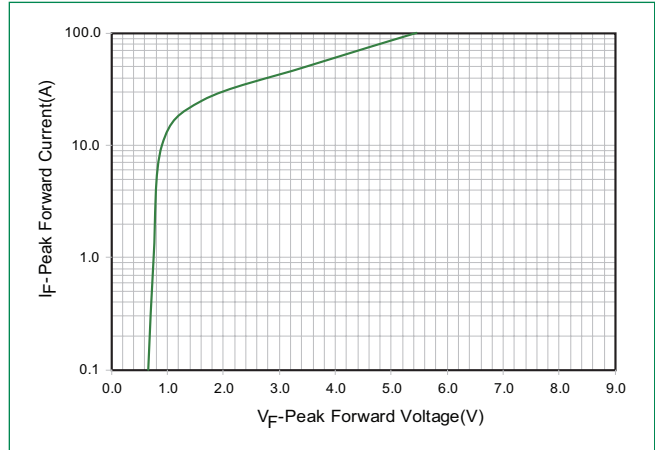


**Ratings and Characteristic Curves** ( $T_A=25^\circ\text{C}$  unless otherwise noted) (Continued)

**Figure 7 - Maximum Non-Repetitive Peak Forward Surge Current Uni-Directional Only**

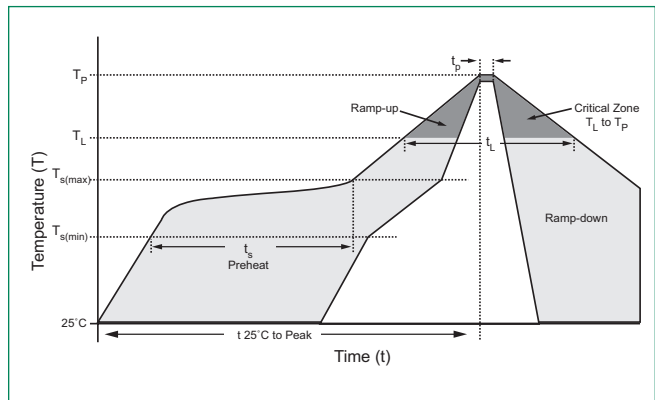


**Figure 8 - Peak Forward Voltage Drop vs Peak Forward Current (Typical Values)**



**Soldering Parameters**

<b>Reflow Condition</b>		Lead-free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 120 secs
<b>Average ramp up rate (Liquidus Temp (<math>T_L</math>) to peak)</b>		3°C/second max
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>		3°C/second max
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Time (min to max) ( $t_r$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>		260 $^{+0/-5}$ °C
<b>Time within 5°C of actual peak Temperature (<math>t_p</math>)</b>		30 seconds max
<b>Ramp-down Rate</b>		6°C/second max
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>		8 minutes max.
<b>Do not exceed</b>		260°C



**Flow/Wave Soldering (Solder Dipping)**

<b>Peak Temperature :</b>	265°C
<b>Dipping Time :</b>	10 seconds
<b>Soldering :</b>	1 time

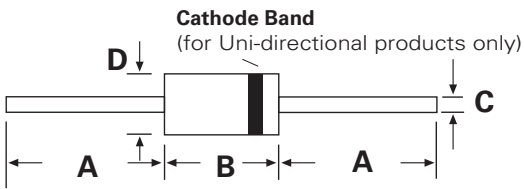
**Physical Specifications**

<b>Weight</b>	0.045oz., 1.2g
<b>Case</b>	JEDEC DO-201 molded plastic body over passivated junction.
<b>Polarity</b>	Color band denotes the cathode except Bipolar.
<b>Terminal</b>	Matte Tin axial leads, solderable per JESD22-B102.

**Environmental Specifications**

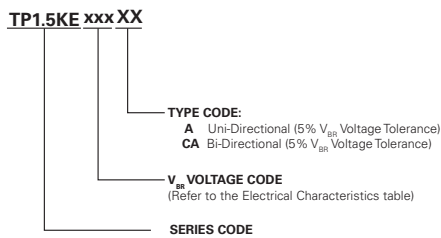
<b>High Temp. Storage</b>	JESD22-A103
<b>HTRB</b>	JESD22-A108
<b>Temperature Cycling</b>	JESD22-A104
<b>H3TRB</b>	JESD22-A101
<b>RSH</b>	JESD22-B106

### Dimensions

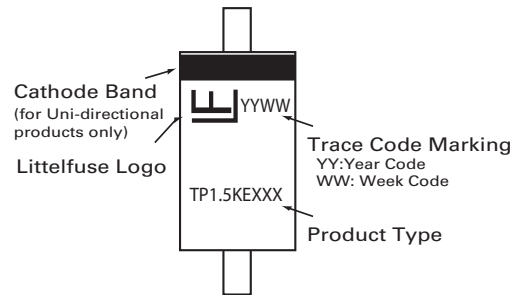


Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
<b>A</b>	1.000	-	25.40	-
<b>B</b>	0.285	0.375	7.20	9.50
<b>C</b>	0.038	0.042	0.96	1.07
<b>D</b>	0.190	0.210	4.80	5.30

### Part Numbering System



### Part Marking System



### Packaging

Part Number	Component Package	Quantity	Packaging Option	Packaging Specification
TP1.5KExxxXX	DO-201	1200	Tape & Reel	EIA STD RS-296

### Tape and Reel Specification

